

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N06S2L-50	**Issued**	16. March 2021
MA#	MA000685674		
Package	PG-TDSON-8-4	**Weight***	96.86 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.164	1.20	1.20	12016	12016
chip_2	inorganic material	silicon	7440-21-3	1.164	1.20	1.20	12016	12016
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	iron	7439-89-6	0.044	0.05		459	
	non noble metal	copper	7440-50-8	44.409	45.86	45.92	458502	459099
wire	non noble metal	aluminium	7429-90-5	0.770	0.80	0.80	7954	7954
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		928	
	plastics	epoxy resin	-	6.383	6.59		65897	
	inorganic material	silicondioxide	60676-86-0	38.475	39.72	46.40	397238	464063
leadfinish	non noble metal	tin	7440-31-5	1.308	1.35	1.35	13501	13501
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	495	496
solder	non noble metal	tin	7440-31-5	0.055	0.06		566	
	noble metal	silver	7440-22-4	0.069	0.07		708	
	non noble metal	lead	7439-92-1	2.620	2.70	2.83	27048	28322
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.245	0.25	0.25	2529	2533
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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